

SEMITRANS[®] 3

IGBT4 Modules

SKM 150GB12T4G

Target Data

Features

- IGBT4 = 4. Generation (Trench) IGBT
- V_{CEsat} with positive temperature coefficient
- High short circuit capability, self limiting to 6 x I_{CNOM}
- Soft switching 4. Generation CAL diode (CAL4)

Typical Applications

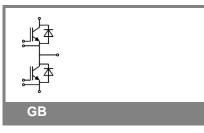
- AC inverter drives
- UPS
- Electronic welders at f_{sw} up to 20 kHz

Remarks

• Case temperature limited to $T_c = 125^{\circ}C$ max, recomm. $T_{op} = -40$... +150°C, product rel. results valid for $T_i \le 150^{\circ}$

Ŭ			= 25 °C, unless otherwise specified			
Symbol	Conditions		Values	Units		
IGBT						
V _{CES}	T _j = 25 °C		1200	V		
I _C	T _j = 175 °C	T _{case} = 25 °C	220	А		
		T _{case} = 80 °C	170	А		
I _{CRM}	$I_{CRM} = 3 \times I_{CNOM}$		450	А		
V _{GES}			± 20	V		
t _{psc}	V_{CC} = 600 V; $V_{GE} \le 15$ V; VCES < 1200 V	T _j = 150 °C	10	μs		
Inverse	Diode		•			
I _F	T _j = 175 °C	T _{case} = 25 °C	180	А		
		T _{case} = 80 °C	135	А		
I _{FRM}	I _{FRM} = 3 x I _{FNOM}		450	А		
I _{FSM}	t _p = 10 ms; sin.	T _j = 175 °C	860	А		
Module						
I _{t(RMS)}			500	А		
T _{vj}			-40 +175	°C		
T _{stg}			-40 +125	°C		
V _{isol}	AC, 1 min.		4000	V		

Conditions $V_{GE} = V_{CE}, I_C = 6 \text{ mA}$ $V_{GE} = 0 \text{ V}, V_{CE} = V_{CES}$	T _j = 25 °C T _i = 25 °C	min. 5	typ. 5,8	max. 6,5	Units
$V_{GE} = 0 V, V_{CE} = V_{CES}$	$T_j = 25 °C$ T. = 25 °C	5	5,8	6,5	V
$V_{GE} = 0 V, V_{CE} = V_{CES}$	T _j = 25 °C T _i = 25 °C	5	5,8	6,5	V
V _{GE} = 0 V, V _{CE} = V _{CES}	T _j = 25 °C T _i = 25 °C				1 -
	T. = 25 °C	1			mA
			0,8	0,9	V
	T _j = 150 °C		0,7	0,8	V
/ _{GE} = 15 V	T _j = 25°C				mΩ
	T _j = 150°C				mΩ
_{Cnom} = 150 A, V _{GE} = 15 V			1,85	2,05	V
	$T_j = 150^{\circ}C_{chiplev.}$		2,25	2,45	V
			9,3		nF
/ _{CE} = 25, V _{GE} = 0 V	f = 1 MHz		,		nF
			0,51		nF
/ _{GE} = -8V /+15V			850		nC
j = 25 °C			5		Ω
					ns
$R_{Gon} = \Omega$					ns
2 -0	I _{Cnom} = 150A		14,8		mJ ns
Goff - 32	J				ns
	GE - CC		14,8		mJ
			1 -		
/ 	_{GE} = -8V /+15V	$_{CE} = 25, V_{GE} = 0 V$ f = 1 MHz $_{GE} = -8V / +15V$ $_{gen} = 25 ^{\circ}C$ $_{Gon} = \Omega$ $V_{CC} = 600V$ $_{I_{Cnom}} = 150A$	$CE = 25, V_{GE} = 0 V \qquad f = 1 \text{ MHz}$ $GE = -8V /+15V$ $F = 25 ^{\circ}C$ $Gon = \Omega \qquad V_{CC} = 600V$ $I_{Cnom} = 150A$ $T_{j} = 150 ^{\circ}C$	$\begin{array}{c} 9,3 \\ 0,58 \\ 0,51 \\ \hline \\ G_{CE} = -8V / +15V \\ 1 = 25 \ ^{\circ}C \\ \hline \\ G_{on} = \Omega \\ \hline \\ G_{off} = \Omega \\ \hline \\ G_{off} = \Omega \\ \hline \\ \\ G_{off} = \Omega \\ \hline \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\$	$\begin{array}{c} 9,3 \\ 0,58 \\ 0,51 \\ \hline \\ G_{GE} = -8V / +15V \\ I = 25 \ ^{\circ}C \\ \hline \\ G_{on} = \Omega \\ \hline \\ G_{off} = \Omega \\ \hline \\ G_{off} = \Omega \\ \hline \\ \\ G_{eff} = \Omega \\ \hline \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\$





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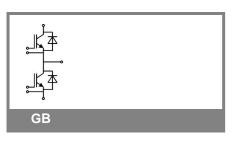
Remarks

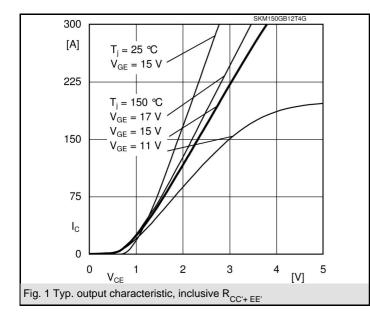
• Case temperature limited to $T_c = 125^{\circ}C$ max, recomm. $T_{op} = -40$... +150°C, product rel. results valid for $T_i \le 150^{\circ}$

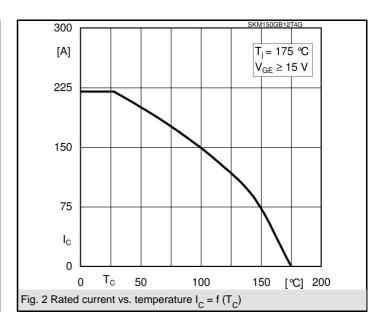
Characte	ristics					
Symbol	Conditions		min.	typ.	max.	Units
Inverse D						
$V_F = V_{EC}$	I_{Fnom} = 150 A; V_{GE} = 0 V			2,2	2,5	V
		T _j = 150 °C _{chiplev.} T _j = 25 °C		2,1	2,45	V
V _{F0}		,		1,3	1,5	V
		T _j = 150 °C		0,9	1,1	V
r _F		T _j = 25 °C		6	6,67	mΩ
		T _j = 150 °C		8	9	mΩ
I _{RRM} Q _{rr}	I _{Fnom} = 150 A	T _j = 150 °C				A µC
E _{rr}	V _{GE} = -15V			11,3		mJ
R _{th(j-c)}	per diode				0,32	K/W
Freewhee	eling Diode					
$V_F = V_{EC}$	I _{Fnom} = A; V _{GE} = V	$T_j = °C_{chiplev.}$				V
V _{F0}		$T_{j} = °C$ $T_{j} = °C$ $T_{j} = °C$				V
r _F		T _i = °C				V
I _{RRM}	I _{Fnom} = A	T _i = °C				А
Q _{rr}						μC
E _{rr}						mJ
	per diode					K/W
Module						
L _{CE}				15	20	nH
R _{CC'+EE'}	res., terminal-chip	T _{case} = 25 °C			0,35	mΩ
		T _{case} = 125 °C			0,5	mΩ
R _{th(c-s)}	per module			0,02	0,038	K/W
M _s	to heat sink M6		3		5	Nm
M _t	to terminals M6		2,5		5	Nm
w					325	g

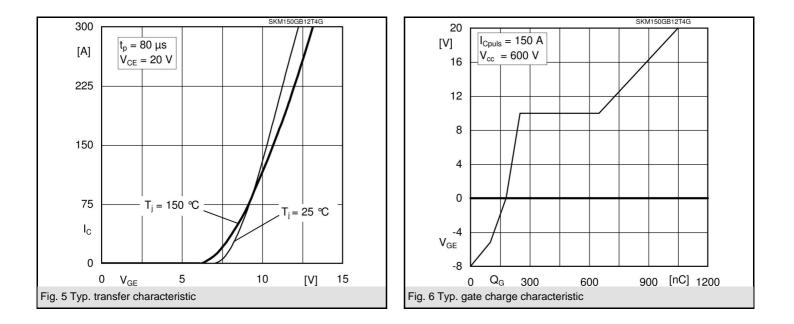
This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

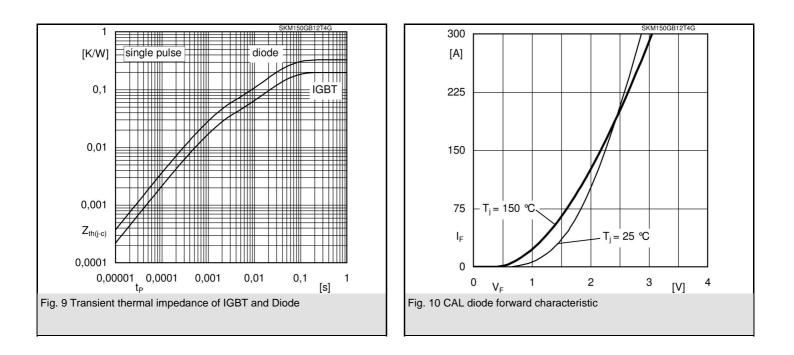
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